# CALL FOR PRESENTATIONS:

## SMTA 3D/SiP/Advanced Packaging Symposium

The SMTA is pleased to bring back this popular advanced packaging event.

**3D/SiP/Advanced Packaging Symposium**
**April 29-30, 2008**
**Washington Duke Inn & Golf Club, Durham, NC**

The 3D/SiP/Advanced Packaging Symposium will provide you with the most up-to-date research in the field of advanced packaging with particular attention to materials, manufacturing, assembly and Package/PWB reliability in a Pb-free environment.  Conference co-chairs Marie Cole, IBM and Daniel Baldwin, Ph.D., Engent, Inc., and the program technical committee invite you to submit an abstract for consideration in this new event.  Please note that there will not be a technical paper requirement for this program.  Speakers will be required to submit presentation slides to the SMTA prior to program.  A suggested topic breakdown is included below.

**Specific subject areas include, but are not limited to, those included below:**

- System in Package (SiP)
- Multi-Chip Packaging (MCP)
- Materials/Finishes/Solder Alloys
- Reliability
- Package on Package (PoP)
- Enabling Technologies
- Die Stacking/3D Assembly
- Wafer-Level Packaging (WLP)

- Bumping/Flip Chip on Board (FCOB)
- Handheld Electronics/Miniaturization
- 3D Wafer Level Integration
- 3D Wafer Level Packaging
- Die/Package/System Co-Design
- Modeling and Simulation
- Drop/Shock/Bend Performance
- Infrastructure

Please provide a 200-300 word abstract to the Conference Coordinator, Melissa Serres.  Abstracts can be submitted via email as a Word document attachment.
**Deadline for abstracts is November 30, 2007.**

Please include the following contact information with abstract: Name, Company, Mailing Address, Telephone Number, Fax Number, E-Mail Address, and Presentation Title.

Questions?    Please contact:
Melissa Serres, Conference Coordinator
Phone: 952-920-7682
Email: melissa@smta.org

**Technical Committee:**
Daniel F. Baldwin, Ph.D. Engent, Inc.
Donald Banks, 3M
Charles E. Bauer, Ph.D., Techlead
Marie Cole, IBM, Inc.
Reza Ghaffarian, Ph.D., JPL/NASA
Donghyun Kim, Cisco Systems
Andrew Mawer, Freescale Semiconductor
Lee Smith, Amkor Technology
Vern Solberg, Solberg Mfg. Technology
Irene Sterian, Celestica, Inc.

**SMTA VP Technical Programs:**
Dr. Ken Gilleo, ET-Trends LLC
ken@et-trends.com